

For structural bonding & staking applications where precise dispensing is required

0161 is a one-component, slightly thixotropic, electrically isolating, precision mixed, degassed, and frozen epoxy. It exhibits low shrinkage once cured and is ideal for gap filling purposes. This product is designed for structural bonding and staking applications where precise dispensing is required. 0161 conforms to HMS-2240 Type IX specifications and can be cured at room temperature.

UNCURED	
Viscosity @ 25°C	55,000 cPs
Thixotropic Index	1.0
Pot Life @ 25°C	1 hour
Shelf Life @ -40°C	6 months
CURE OPTIONS	1 hour @ 93°C 7 days @ 25°C
CURED PROPERTIES	Based on cure of 1 hour @ 93°C
Color	Green
Shore D Hardness	88
Glass Transition Temp (°C)	87
Lap Shear 2024T3 Clad (psi)	3,500
ELECTRICAL PROPERTIES	Based on cure of 1 hour @ 93°C
Dielectric Constant	3.4 @ 1000 Hz
Dissipation Factor	0.05 @ 1000 Hz
Volume Resistivity (ohm-cm)	1.0E 15 @ 500 VDC
THERMAL PROPERTIES	Based on cure of 1 hour @ 93°C
Glass Transition Temp (°C)	87
OUTGASSING PROPERTIES	Based on cure of 1 hour @ 93°C
TML (%)	0.27
CVCM (%)	0.01
WVR (%)	0.32

KEY FEATURES

Bonds Well to Most Substrates

Electrically Isolating

Gap Filling

Meets NASA Outgassing

HMS 2240, Type IX

Low Shrinkage

Room or Elevated Temperature Cure

User-friendly Packaging

Talk to an engineer:

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